



Product Change Notification: DSNO-080VTT016

Date:

16-May-2025

Product Category:

Analog Temperature Sensors, Battery Management and Fuel Gauges - Battery Chargers, Digital Potentiometers, Digital Temperature Sensors, Linear Op Amps

Notification Subject:

CCB 7291.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP4014, MCP4024, MCP6421, MCP6471, MCP6481, MCP6491, MCP6V11xx, MCP6V16xx, MCP6V31xx, MCP6V36xx, MCP6V61xx, MCP6V66xx, MCP6V71xx, MCP6V76xx, MCP6V81xx, MCP6V86xx, MCP6V91xx, MCP6V96xx, MCP73811, MCP73812, MCP73831, MCP73832, MCP9501, MCP9502, MCP9503, MCP9504, MCP9509, MCP9800, MCP9802 and MIC333 device families in 5L SOT-23 package at MTAI assembly site.

Affected CPNs:

[DSNO-080VTT016_Affected_CPN_05162025.pdf](#)

[DSNO-080VTT016_Affected_CPN_05162025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP4014, MCP4024, MCP6421, MCP6471, MCP6481, MCP6491, MCP6V11xx, MCP6V16xx, MCP6V31xx, MCP6V36xx, MCP6V61xx, MCP6V66xx, MCP6V71xx, MCP6V76xx, MCP6V81xx, MCP6V86xx, MCP6V91xx, MCP6V96xx, MCP73811, MCP73812, MCP73831, MCP73832, MCP9501, MCP9502, MCP9503, MCP9504, MCP9509, MCP9800, MCP9802 and MIC333 device families in 5L SOT-23 package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
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Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)
Wire Material	Au	CuPdAu
Die Attach Material	8900NC	8006NS
Molding Compound Material	G600V	G600V
Lead-Frame Material	A194	A194
DAP Surface Prep	Ag Spot Plated	Ag Single Ring Plated
Lead-Frame Design	See Pre and Post Change Summary attachment for comparison.	

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 08 July 2025 (date code: 2528)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2025					>	July 2025				
Work Week	18	19	20	21	22		27	28	29	30	31
Qual Report Availability			X								
Final PCN Issue Date			X								
Estimated Implementation Date								X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: May 16, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-080VTT016_Qualification_Report.pdf

PCN_DSNO-080VTT016_Pre and Post Change_Summary.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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